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Abstract: The proceedings contain 20 papers. The topics discussed include: analysis of factors affecting the information sharing on fin-tech peer to peer lending; anonymity and trust roles in the digital barter age: digital transformation framework and digital assets popularity assessment; external auditors' perception of use of virtual reality in financial statement auditing process; the path of artificial intelligence technology to reduce cost and increase efficiency of e-commerce supply chain; customer preferences for online games: a conjoint analysis approach with market segmentation; study on budget preparation and forecast model based on Apriori rule algorithm; train operation scheme based on grey correlation degree; analysis of fraudulent financial reporting based on fraud heptagon model in transportation and logistics industry listed on IDX during Covid-19 pandemic; a study on the construction of human resources audit management platform based on big data; design and implementation of intelligent warehouse platform based on ElasticSearch; and proposed conceptual design of artificial intelligence integration into a pressure oxidation facility.

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